

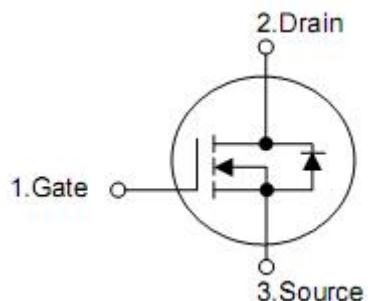
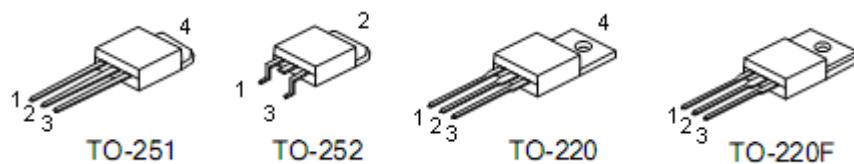
1. Features

- $R_{DS(ON)} = 1.9\Omega$ (typ.) @ $V_{GS} = 10V$, $I_D = 2A$
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

2. Application

- High frequency switching mode power supply
- Uninterruptible Power Supply(UPS)
- Electronic ballast

3. Pin configuration



Pin	Function
1	Gate
2	Drain
3	Source
4	Drain

4. Ordering Information

Part Number	Package	Brand
KND4360A	TO-252	KIA
KNU4360A	TO-251	KIA
KNP4360A	TO-220	KIA
KNF4360A	TO-220F	KIA

5. Absolute maximum ratings

(T _c = 25°C , unless otherwise specified)						
Parameter		Symbol	Rating			
			TO220	TO220F	TO251	TO252
Drain-source voltage		V _{DSS}	600			
Gate-source voltage		V _{GSS}	±30			
Drain current continuous	T _c =25°C	I _D	4.0	4.0*	4 *	A
	T _c =100°C		2.78	2.78*	2.78*	A
Drain current pulsed (note1)		I _{DM}	16	16*	16*	A
Avalanche energy	Single pulse (note2)	E _{AS}	180			
Peak diode recovery dv/dt (note3)		dv/dt	4.8			
Total power dissipation	T _c =25°C	P _D	100	44.6	44.6	W
	Derate above 25°C		0.8	0.357	0.357	W/°C
Thermal Resistance Junction to Case		R _{θJC}	1.25	3.75	2.8	°C/W
Storage temperature		T _{STG}	-55~+150			

*Drain current limited by maximum junction temperature.

6. Electrical characteristics

($T_J=25^\circ\text{C}$, unless otherwise notes)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Off characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	600	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}}=600\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
		$V_{\text{DS}}=480\text{V}, T_C=125^\circ\text{C}$	-	-	10	μA
Gate-body leakage Current	I_{GSS}	$V_{\text{GS}}=30\text{V}, V_{\text{DS}}=0\text{V}$	-	-	100	nA
		$V_{\text{GS}}=-30\text{V}, V_{\text{DS}}=0\text{V}$	-	-	-100	nA
Breakdown voltage temperature coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to 25°C $I_{\text{D}}=250\mu\text{A}$	-	0.65	-	$\text{V}/^\circ\text{C}$
On characteristics						
Gate threshold voltage (note4)	$V_{\text{GS}(\text{TH})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2.0	-	4.0	V
Static drain-source on-resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=2.0\text{A}$	-	1.9	2.3	Ω
Forward Transconductance	G_{FS}	$V_{\text{DS}}=30\text{V}, I_{\text{D}}=2.0\text{A}$	-	5.5	-	S
Dynamic characteristics						
Input capacitance	C_{ISS}	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	-	511	-	pF
Output capacitance	C_{OSS}		-	56.6	-	pF
Reverse transfer capacitance	C_{RSS}		-	5.55	-	pF
Switching characteristics						
Turn-on delay time	$t_{\text{D}(\text{ON})}$	$V_{\text{DD}}=300\text{V}, I_{\text{D}}=4.0\text{A}, R_G=10\Omega, V_{\text{GS}}=10\text{V}$	-	11.3	-	ns
Rise time	t_R		-	14.7	-	ns
Turn-off delay time	$t_{\text{D}(\text{OFF})}$		-	37.6	-	ns
Fall time	t_F		-	10.4	-	ns
Total gate charge	Q_G	$V_{\text{DD}}=480\text{V}, I_{\text{D}}=4.0\text{A}$	-	15.3	-	nC
Gate-source charge	Q_{GS}		-	2.45	-	nC
Gate-drain charge	Q_{GD}		-	6.56	-	nC
Drain-source diode characteristics						
Drain-source diode forward voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{SD}}=4.0\text{A}$	-	-	1.4	V
Continuous drain-source current	I_{SD}		-	-	4	A
Pulsed drain-source current	I_{SM}		-	-	16	A
Reverse recovery time	t_{RR}	$V_{\text{GS}}=0\text{V}, I_{\text{F}}=4\text{A}$ $dI/dt=100\text{A}/\mu\text{s}$	-	315	-	ns
			-	1.83	-	μC

Notes: 1. Repetitive rating : pulse width limited by maximum junction temperature

2. $L=10\text{mH}, I_{\text{AS}}=6.0\text{A}, V_{\text{DD}}=50\text{V}, R_G=25\Omega$, starting $T_J=25^\circ\text{C}$

3. $I_{\text{SD}} \leq 4.0\text{A}, dI/dt \leq 200\text{A}/\mu\text{s}$, $V_{\text{DD}} \leq \text{BV}_{\text{DSS}}$, starting $T_J=25^\circ\text{C}$

4. Pulse test : pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$

7. Test circuits and waveforms

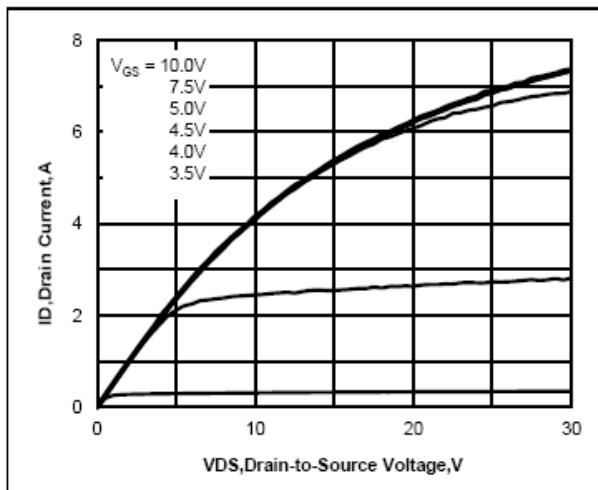


Figure 1. Output Characteristics

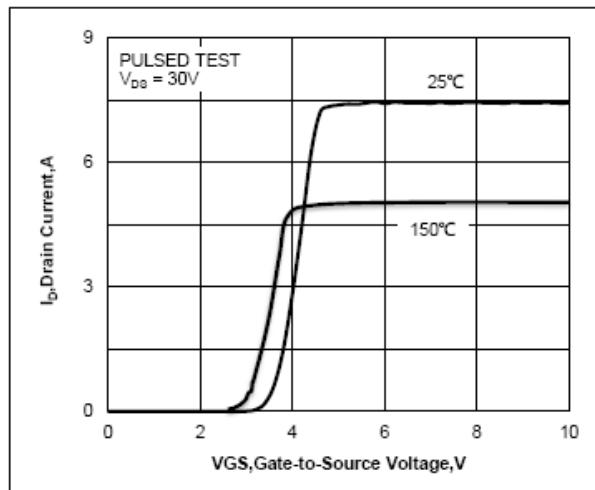
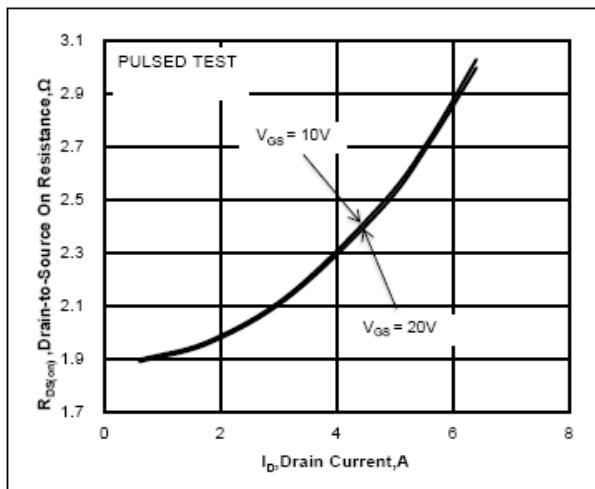
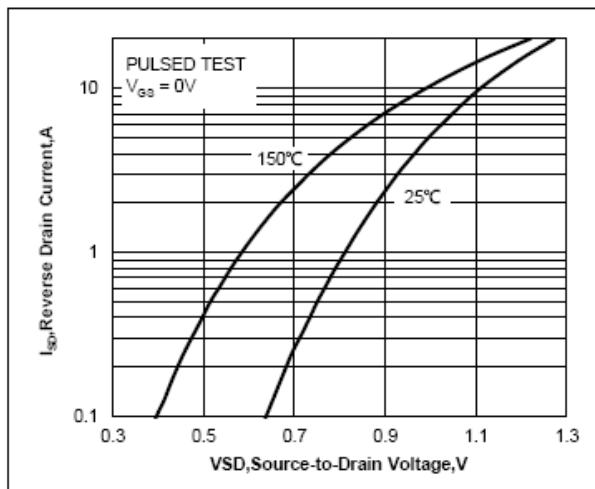


Figure 2. Transfer Characteristics



**Figure 3. Drain-to-Source On Resistance vs.
Drain Current and Gate Voltage**



**Figure 4. Body Diode Forward Voltage vs.
Source Current and Temperature**

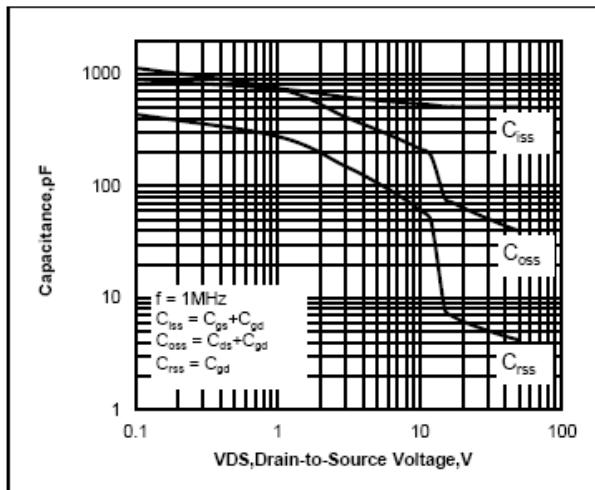


Figure 5. Capacitance Characteristics

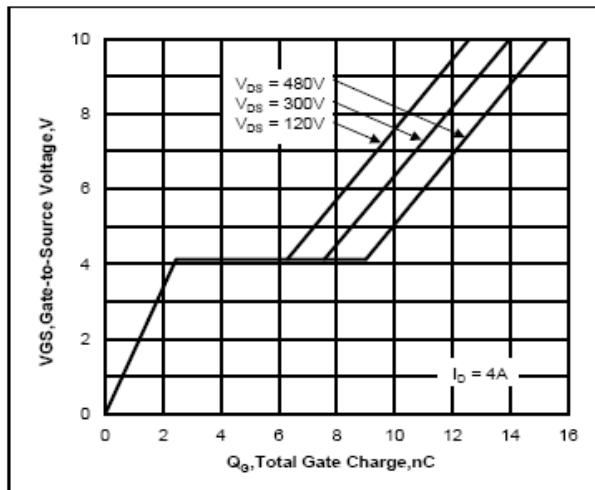
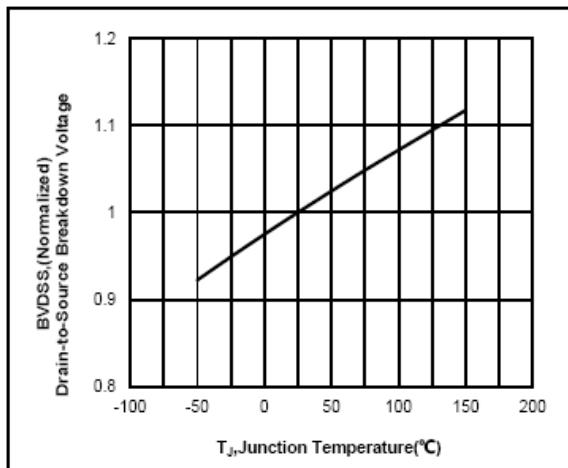
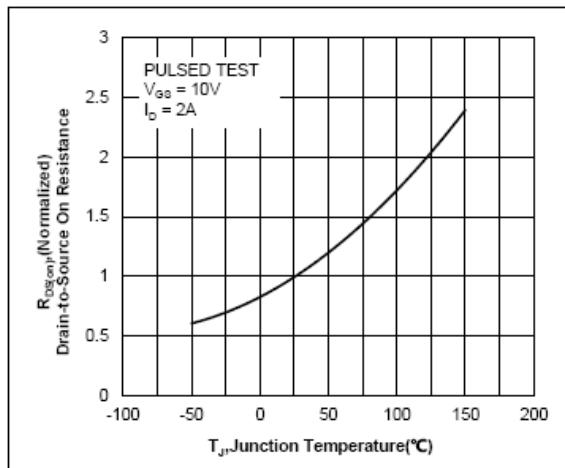


Figure 6. Gate Charge Characteristics



**Figure 7. Normalized Breakdown Voltage vs.
Junction Temperature**



**Figure 8. Normalized On Resistance vs.
Junction Temperature**

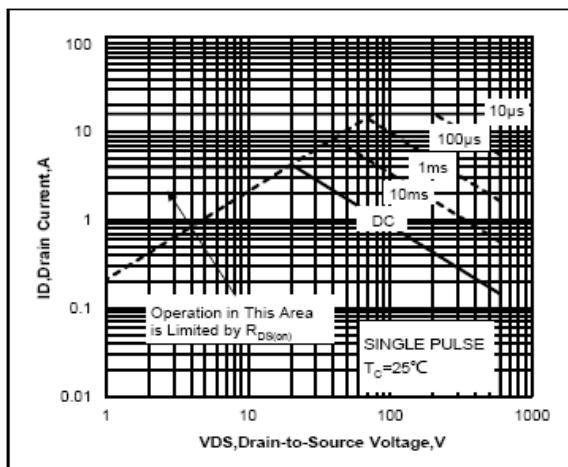
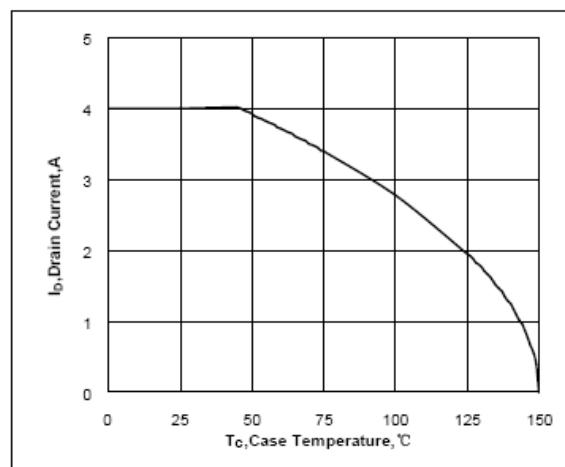


Figure 9. Maximum Safe Operating Area



**Figure 10. Maximum Continuous Drain Current vs.
Case Temperature**

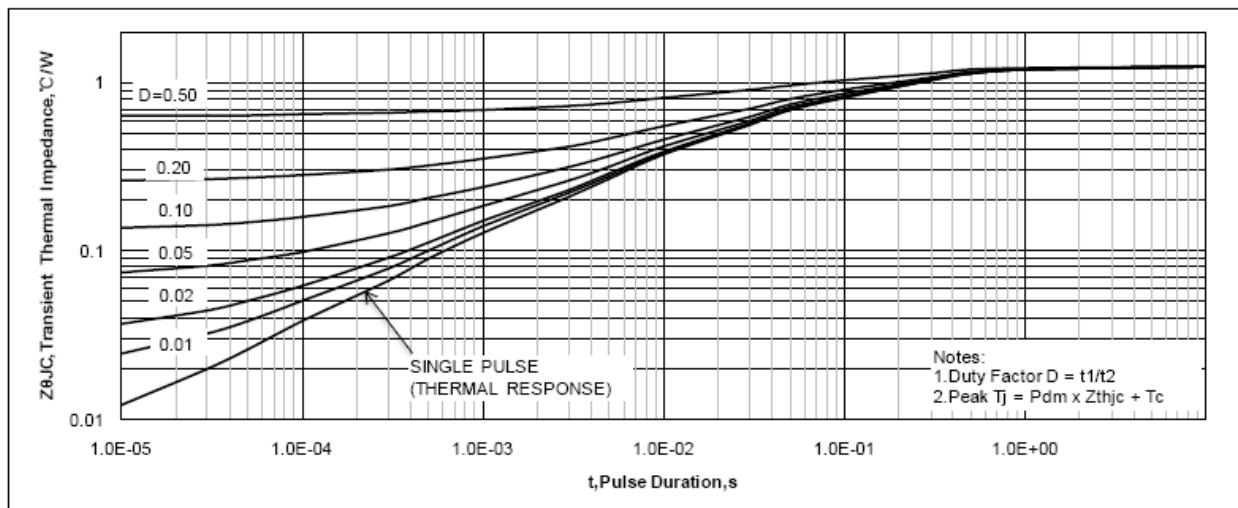


Figure 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

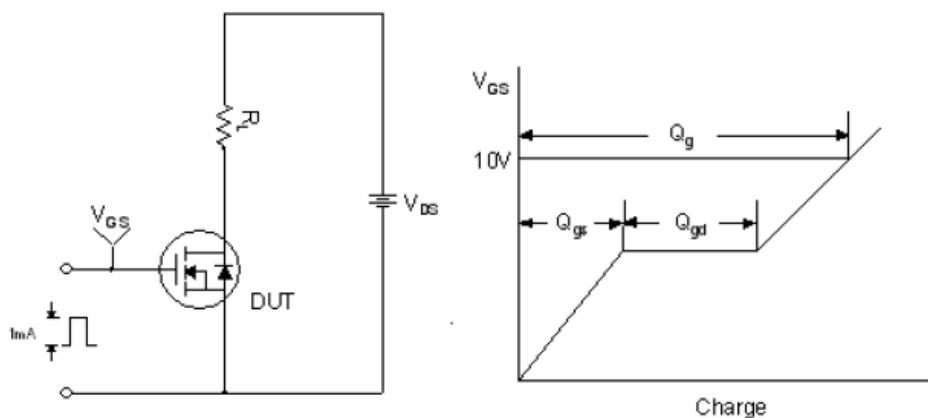


Figure 12. Gate Charge Test Circuit & Waveform

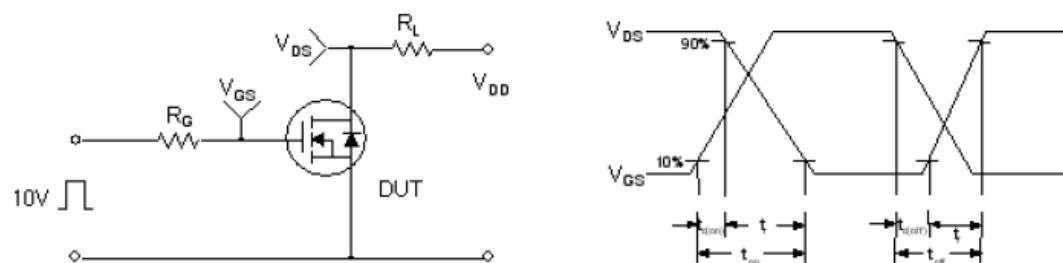


Figure 13. Resistive Switching Test Circuit & Waveforms

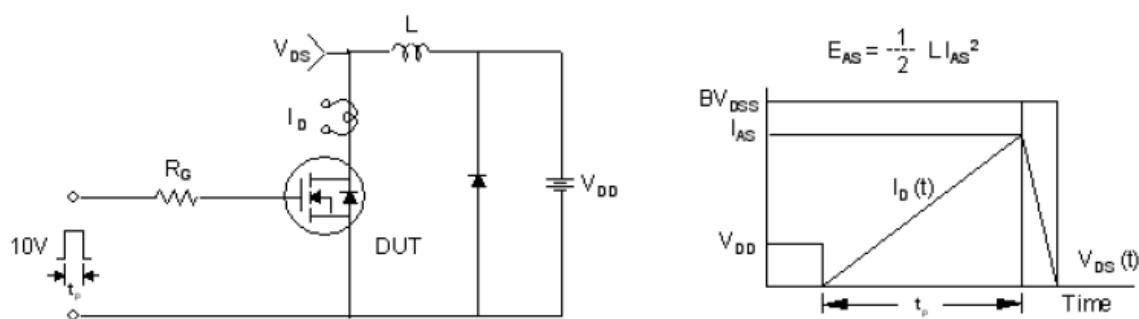
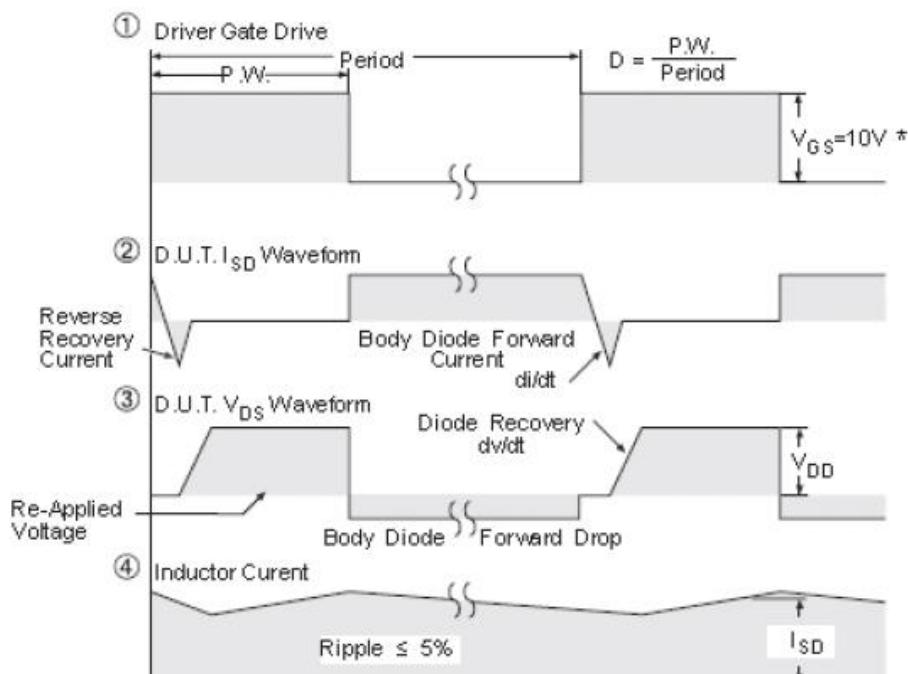
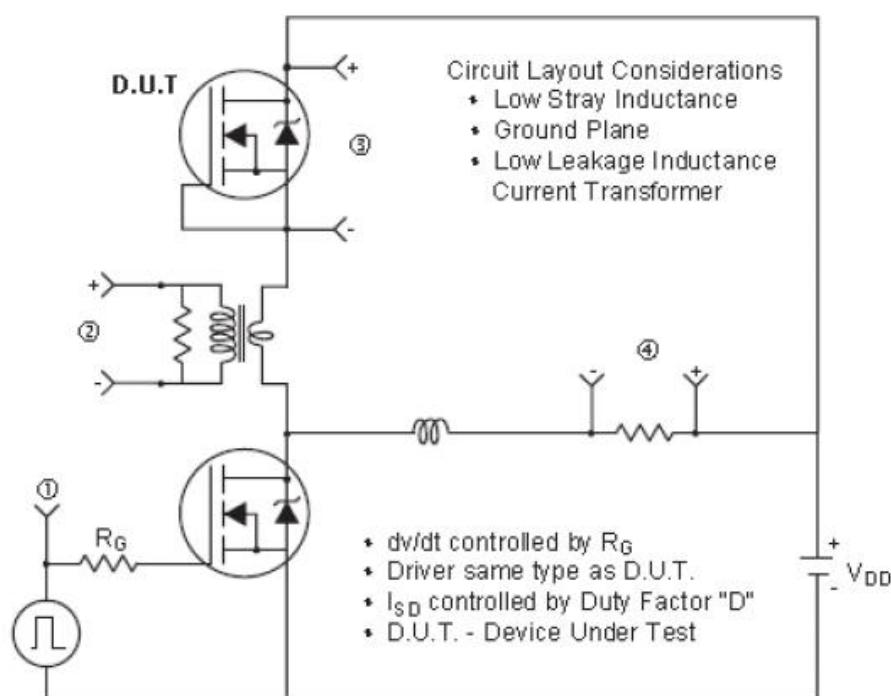


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



* $V_{GS} = 5V$ for Logic Level Devices

Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms (For N-channel)